





## FPAB30BH60

# Smart Power Module(SPM®) for Front-End Rectifier

## **General Description**

FPAB30BH60 is an advanced smart power module(SPM®) of PFC(Power Factor Correction) that Fairchild has newly developed and designed mainly targeting mid-power application especially for an air conditioners. It combines optimized circuit protection and drive IC matched to high frequency switching IGBTs. System reliability is futher enhanced by the integrated under-voltage lock-out and over-current protection function.

### **Features**

- Low thermal resistance due to Al<sub>2</sub>O<sub>3</sub>-DBC substrate
- 600V-30A 1-phase IGBT PWM semi-converter including a drive IC for gate driving and protection
- · Typical switching frequency of 20kHz
- · Isolation rating of 2500Vrms/min.

### **Applications**

• AC 85V ~ 264V single-phase front-end rectifier

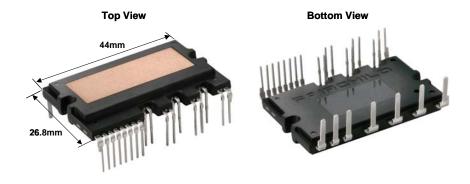


Fig. 1.

## **Integrated Power Functions**

• PFC converter for single-phase AC/DC power conversion (Please refer to Fig. 3)

## **Integrated Drive, Protection and System Control Functions**

- For IGBTs: Gate drive circuit, Overcurrent circuit protection (OC), Control supply circuit under-voltage (UV) protection
- Fault signaling: Corresponding to a UV fault
- Input interface: 5V CMOS/LSTTL compatible, Schmitt trigger input

## **Pin Configuration**

## **Top View**

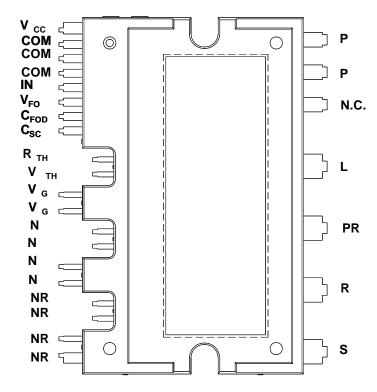


Fig. 2.

# **Pin Descriptions**

Pin Number	Pin Name	Pin Description	
1	V <sub>CC</sub>	Common Bias Voltage for IC and IGBTs Driving	
2,3,4	COM	Common Supply Ground	
5	IN <sub>(R)</sub>	Signal Input for Low-side R-phase IGBT	
6	$V_{FO}$	Fault Output	
7	C <sub>FOD</sub>	Capacitor for Fault Output Duration Time Selection	
8	$c_{sc}$	Capacitor (Low-pass Filter) for Over Current Detection	
9	R <sub>(TH)</sub>	NTC Thermistor terminal	
10	V <sub>(TH)</sub>	NTC Thermistor terminal	
11,12	Vg	IGBT gate dummy	
13~16	Z	IGBT emitter	
17~20	N <sub>R</sub> Negative DC-Link of Rectifier		
21,22	21,22 P Positive Rail of DC–Link		
23	N.C	No Connection	
24	L	Reactor connection pin	
25	$P_{R}$	Positive DC-Link of Rectifier	
26	R	AC input for R-phase	
27	S	AC input for S-phase	

# **Internal Equivalent Circuit and Input/Output Pins**

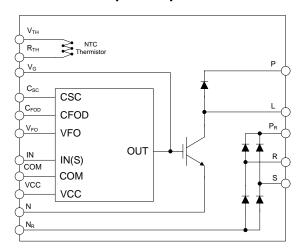


Fig. 3.

## **Package Marking & Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FPAB30BH60	FPAB30BH60	SPM27-IA	-	-	10

# **Absolute Maximum Ratings** ( $T_J = 25^{\circ}C$ , Unless Otherwise Specified)

## **Converter Part**

Item	Symbol	Condition	Rating	Unit
Supply Voltage	V <sub>i</sub>	Applied between R-S	264	$V_{RMS}$
Supply Voltage (Surge)	V <sub>i(Surge)</sub>	Applied between R-S	500	V
Output Voltage	V <sub>PN</sub>	Applied between P- N	450	V
Output Voltage (Surge)	V <sub>PN(Surge)</sub>	Applied between P- N	500	V
Collector-emitter Voltage	V <sub>CES</sub>		600	V
Input Current (100% Load)	l <sub>i</sub>	$T_C$ < 95°C, $V_i$ =220V, $V_{PN}$ = 390V, $V_{PWM}$ =20kHz	25	Α
Input Current (125% Load) I <sub>i(1</sub>		$T_C$ < 95°C, $V_i$ =220V, $V_{PN}$ = 390V, $V_{PWM}$ =20kHz, 1min Non-repetitive	30	А
Collector Dissipation	P <sub>C</sub>	T <sub>C</sub> = 25°C per One IGBT	169	W
Operating Junction Temperature T <sub>J</sub>		(Note 1)	-20 ~ 150	°C

## **Control Part**

Item	Symbol	Condition	Rating	Unit
Control Supply Voltage	V <sub>CC</sub>	Applied between V <sub>CC</sub> - COM	20	V
Input Signal Voltage	V <sub>IN</sub>	Applied between IN - COM	-0.3~5.5	V
Fault Output Supply Voltage	V <sub>FO</sub>	Applied between V <sub>FO</sub> - COM	-0.3~V <sub>CC</sub> +0.3	V
Fault Output Current	I <sub>FO</sub>	Sink Current at V <sub>FO</sub> Pin	5	mA
Current Sensing Input Voltage	$V_{SC}$	Applied between C <sub>SC</sub> - COM	-0.3~V <sub>CC</sub> +0.3	V

## **Total System**

Item	Symbol	Condition	Rating	Unit
Module Case Operation Temperature	T <sub>C</sub>		-20 ~ 100	°C
Storage Temperature	T <sub>STG</sub>		-40 ~ 125	°C
Isolation Voltage	V <sub>ISO</sub>	60Hz, Sinusoidal, AC 1 minute, Connection Pins to DBC	2500	$V_{rms}$

## **Thermal Resistance**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Junction to Case Thermal	$R_{\theta(j-c)Q}$	IGBT	-	-	0.74	°C/W
Resistance	$R_{\theta(j-c)F}$	FRD	-	-	1.44	°C/W
(Referenced to PKG center)	$R_{\theta(i-c)R}$	Rectifier	-	-	2.07	°C/W

2. For the measurement point of case temperature( $T_{\mbox{\scriptsize C}}$ ), please refer to Fig. 2.

Note 1. The maximum junction temperature rating of the power chips integrated within the SPM® is 150 °C(@T<sub>C</sub>  $\leq$  100°C). However, to insure safe operation of the SPM®, the average junction temperature should be limited to T<sub>J(ave)</sub>  $\leq$  125°C (@T<sub>C</sub>  $\leq$  100°C)

# **Electrical Characteristics** ( $T_J = 25$ °C, Unless Otherwise Specified)

## **Converter Part**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
IGBT saturation voltage	V <sub>CE(sat)</sub>	$V_{CC} = 15V, V_{IN} = 5V; I_{C} = 30A$	-	2.0	2.8	V
FRD forward voltage	V <sub>FF</sub>	I <sub>F</sub> = 30A	-	1.8	2.5	V
Rectifier forward voltage	$V_{FR}$	I <sub>F</sub> = 30A	-	1.2	1.5	V
Switching Times	t <sub>ON</sub>	$V_{PN} = 400V, V_{CC} = 15V, I_{C} = 30A$	-	650	-	ns
	t <sub>C(ON)</sub>	V <sub>IN</sub> = 0V ↔ 5V, Inductive Load	-	400	-	ns
	t <sub>OFF</sub>	(Note 3)	-	620	-	ns
	t <sub>C(OFF)</sub>	(1000 0)	-	200	-	ns
	t <sub>rr</sub>		-	60	-	ns
	I <sub>rr</sub>		-	3.5	-	Α
Collector - emitter Leakage Current	I <sub>CES</sub>	$V_{CE} = V_{CES}$	-	-	250	μΑ

## **Control Part**

Item	Symbol	Condition		Min.	Тур.	Max.	Unit
Quiescent V <sub>CC</sub> Supply Current	I <sub>QCCL</sub>	V <sub>CC</sub> = 15V, IN = 0V	V <sub>CC</sub> - COM	-	-	26	mA
Fault Output Voltage	$V_{FOH}$	V <sub>SC</sub> = 0V, V <sub>FO</sub> Circui	t: 4.7kΩ to 5V Pull-up	4.5	-	-	V
	$V_{FOL}$	V <sub>SC</sub> = 1V, V <sub>FO</sub> Circui	V <sub>SC</sub> = 1V, V <sub>FO</sub> Circuit: 4.7kΩ to 5V Pull-up		-	0.8	V
Over Current Trip Level	V <sub>SC(ref)</sub>	V <sub>CC</sub> = 15V	0.45	0.5	0.55	V	
Supply Circuit Under-	UV <sub>CCD</sub>	Detection Level		10.7	11.9	13.0	V
Voltage Protection	UV <sub>CCR</sub>	Reset Level		11.2	12.4	13.2	V
Fault-out Pulse Width	t <sub>FOD</sub>	C <sub>FOD</sub> = 33nF (Note 4)		1.4	1.8	2.0	ms
ON Threshold Voltage	V <sub>IN(ON)</sub>	Applied between IN - COM		3.0	-	-	V
OFF Threshold Voltage	V <sub>IN(OFF)</sub>			-	-	0.8	V
Resistance of Thermistor	R <sub>TH</sub>	@ T <sub>C</sub> = 25°C (Note Fig. 9)		-	50	-	kΩ
		@ T <sub>C</sub> = 100°C (Note Fig. 9)		-	2.99	-	kΩ

Note
 t<sub>ON</sub> and t<sub>OFF</sub> include the propagation delay time of the internal drive IC. t<sub>C(ON)</sub> and t<sub>C(OFF)</sub> are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Fig. 4

Note
4. The fault-out pulse width  $t_{FOD}$  depends on the capacitance value of  $C_{FOD}$  according to the following approximate equation :  $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}[F]$ 

## **Electrical Characteristics**

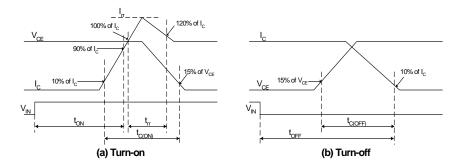


Fig. 4. Switching Time Definition

## **Mechanical Characteristics and Ratings**

Item			Units			
ntem		Condition			Max.	Units
Mounting Torque	Mounting Screw: - M3	Recommended 0.62N•m	0.51	0.62	0.72	N•m
Device Flatness	Note Fig. 5		0	-	+120	μ <b>m</b>
Weight			-	15.00	-	g

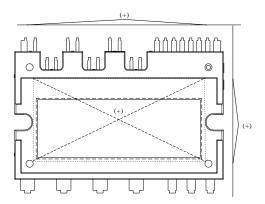
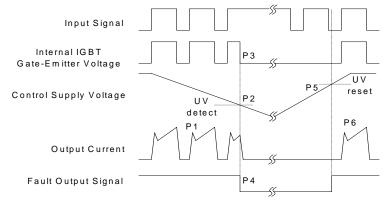


Fig. 5. Flatness Measurement Position

## **Time Charts of SPMs Protective Function**

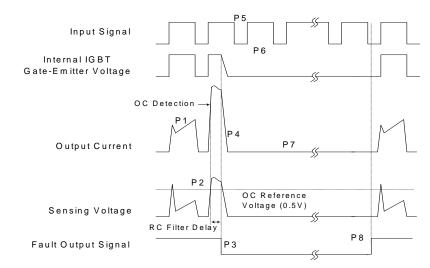


P1: Normal operation - IGBT ON and conducting current

P2 : Under voltage detection P3 : IGBT gate interrupt P4 : Fault signal generation P5 : Under voltage reset

P6: Normal operation - IGBT ON and conducting current

Fig. 6. Under-Voltage Protection



P1: Normal operation - IGBT ON and conducting current

P2 : Over current detection

P3: IGBT gate interrupt / Fault signal generation

P4: IGBT is slowly turned off P5: IGBT OFF signal

P6: IGBT ON signal - but IGBT cannot be turned on during the fault Output activation

P7: IGBT OFF state

P8: Fault Output reset and normal operation start

Fig. 7. Over Current Protection

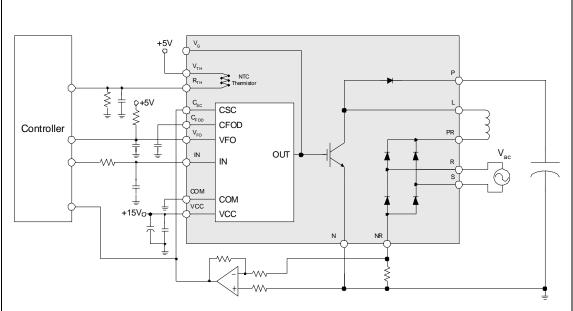


Fig. 8. Application Example

R-T Graph

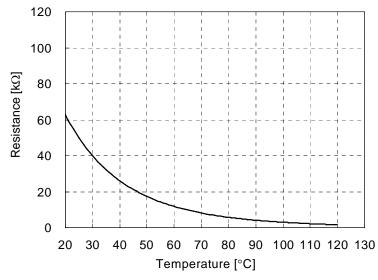
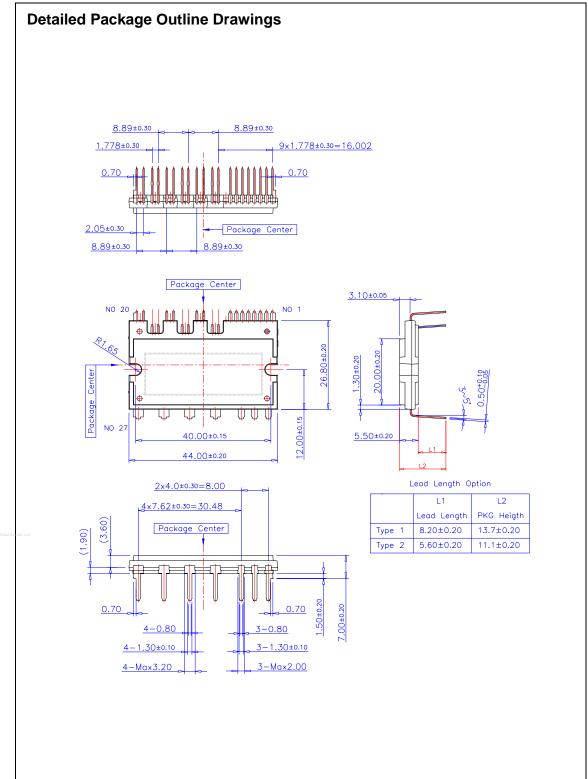
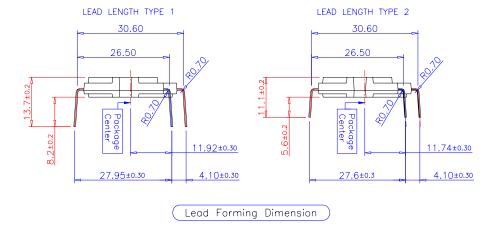
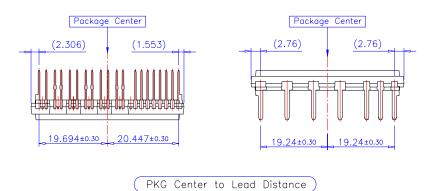


Fig. 9. R-T Curve of the Built-in Thermistor

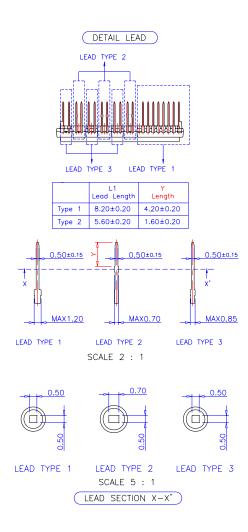


# **Detailed Package Outline Drawings**





# **Detailed Package Outline Drawings**







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